

Supplementary Information

Self-assembled TiN-metal nanocomposites integrated on flexible mica substrates towards flexible devices

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Matrix	Nanopillar	Substrate	Transmittance peaks (nm)	Coercivity [IP, OP] (Oe)	Ref
TiN	NiO	MgO	500, 620	-, 19.157	47
TiN	NiO(core)+Au(shell)	MgO		40.91, 13.81	53
TiN	Au	MgO	400	-	16
TiN & BTO	Au	MgO	490, 600	-	43
TiN	Ag	MgO	374, 350	-	50
TiN	Au-Ni	Mica	470, 515	102.5, 144.3	This work

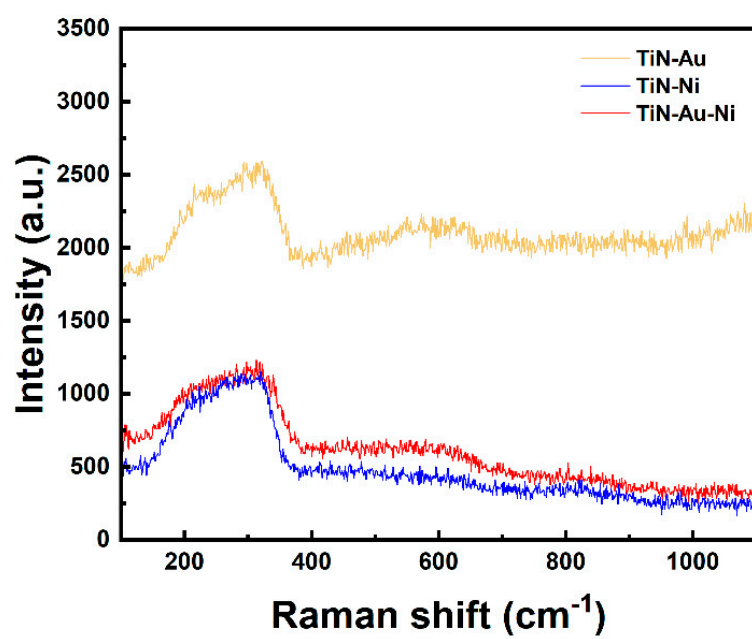


Figure S1. Raman measurement of the TiN-Au, TiN- Ni and TiN-Au-Ni film.